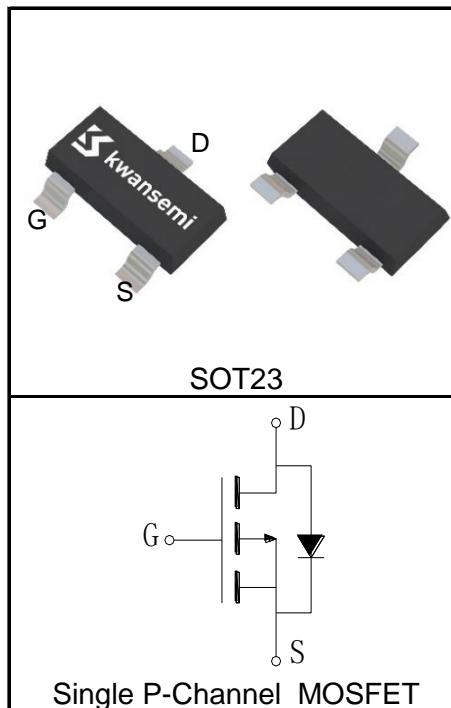


Features

- -30V/-3.4A,
 $R_{DS(ON)} = 48m\Omega$ (Typ.)@ $V_{GS}=-10V$
- $R_{DS(ON)} = 65m\Omega$ (Typ.)@ $V_{GS}=-4.5V$
- Low $R_{DS(ON)}$
- Super High Dense Cell Design
- Reliable and Rugged

Pin Description



Applications

- Load Switch



Halogen-Free

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
Common Ratings ($T_A=25^\circ C$ Unless Otherwise Noted)			
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 20	
T_{Jmax}	Maximum Junction Temperature	150	$^\circ C$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to 150	$^\circ C$
I_S	Diode Continuous Forward Current	$T_A=25^\circ C$	-1.1 A

Mounted on Large Heat Sink

$I_{DP}^{(1)}$	Pulse Drain Current	$T_A=25^\circ C$	-13	A
$I_D^{(2)}$	Continuous Drain Current($V_{GS}=-10V$)	$T_A=25^\circ C$	-3.4	A
		$T_A=70^\circ C$	-2.7	
P_D	Maximum Power Dissipation	$T_A=25^\circ C$	1	W
		$T_A=70^\circ C$	0.64	
$R_{\theta JL}$	Thermal Resistance-Junction to Lead	80	$^\circ C/W$	
$R_{\theta JA}^{(3)}$	Thermal Resistance-Junction to Ambient	125	$^\circ C/W$	

Drain-Source Avalanche Ratings

$E_{AS}^{(4)}$	Avalanche Energy, Single Pulsed	12	mJ
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Electrical Characteristics ($T_A=25^\circ\text{C}$ Unless Otherwise Noted)

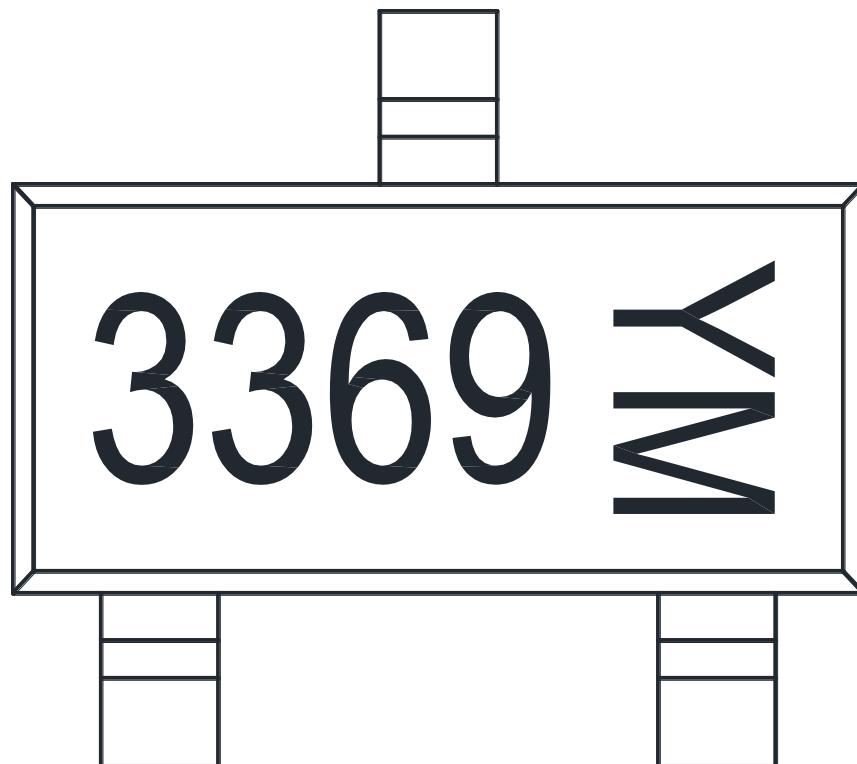
Symbol	Parameter	Test Condition	KS3369AA			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{DS}}=-250\mu\text{A}$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$			-1	μA
		$T_J=125^\circ\text{C}$			-30	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{DS}}=-250\mu\text{A}$	-1.1	-1.6	-2.3	V
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$			± 100	nA
$R_{\text{DS}(\text{ON})}^{(5)}$	Drain-Source On-state Resistance	$V_{\text{GS}}=-10\text{V}, I_{\text{DS}}=-3\text{A}$		48	58	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{DS}}=-2\text{A}$		65	85	$\text{m}\Omega$
Diode Characteristics						
$V_{\text{SD}}^{(5)}$	Diode Forward Voltage	$I_{\text{SD}}=-3\text{A}, V_{\text{GS}}=0\text{V}$		-0.85	-1.2	V
t_{rr}	Reverse Recovery Time	$I_{\text{SD}}=-3\text{A}, dI_{\text{SD}}/dt=-100\text{A}/\mu\text{s}$		14		ns
Q_{rr}	Reverse Recovery Charge			10		nC
Dynamic Characteristics ⁽⁶⁾						
R_{G}	Gate Resistance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$		90		Ω
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-15\text{V}, \text{Frequency}=1.0\text{MHz}$		310		pF
C_{oss}	Output Capacitance			45		
C_{rss}	Reverse Transfer Capacitance			30		
$t_{\text{d}(\text{ON})}$	Turn-on Delay Time	$V_{\text{DD}}=-15\text{V}, I_{\text{DS}}=-3\text{A}, V_{\text{GEN}}=-10\text{V}, R_{\text{G}}=6\Omega$		7		ns
t_{r}	Turn-on Rise Time			9		
$t_{\text{d}(\text{OFF})}$	Turn-off Delay Time			14		
t_{f}	Turn-off Fall Time			6		
Gate Charge Characteristics ⁽⁶⁾						
Q_g	Total Gate Charge	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=-10\text{V}, I_{\text{DS}}=-3\text{A}$		8.2		nC
Q_{gs}	Gate-Source Charge			1.6		
Q_{gd}	Gate-Drain Charge			2		

Notes:

- ①Pulse width limited by safe operating area.
- ②Calculated continuous current based on maximum allowable junction temperature.
- ③When mounted on 1 inch square copper board, $t \leq 10\text{sec}$. The value in any given application depends on the user's specific board design.
- ④Limited by $T_{J\text{max}}$, Starting $T_J = 25^\circ\text{C}$, $I_{AS\text{max}} = -7\text{A}$, $L = 0.5\text{mH}$, $V_{\text{DD}}=-20\text{V}$, $R_{\text{G}} = 25\Omega$, $V_{\text{GS}} = -10\text{V}$. Part not recommended for use above this value.
- ⑤Pulse test; Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- ⑥Guaranteed by design, not subject to production testing.

Ordering and Marking Information

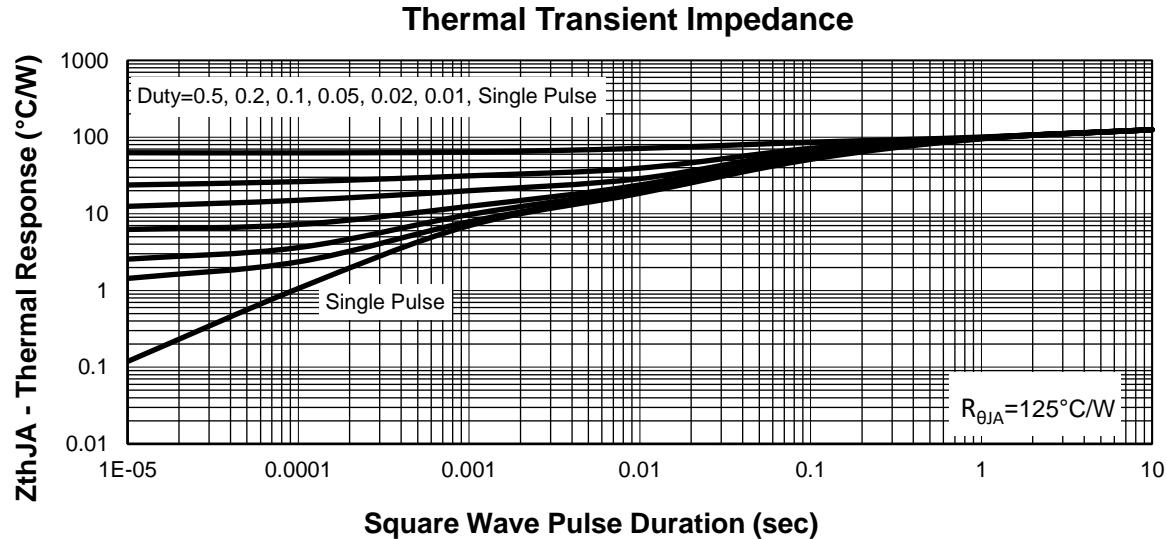
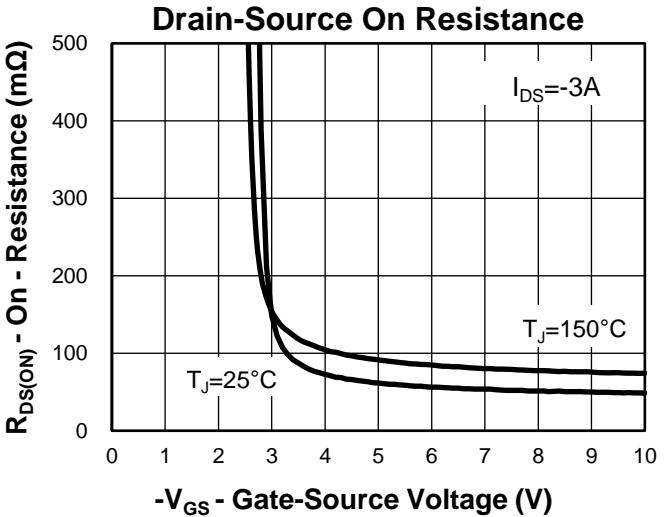
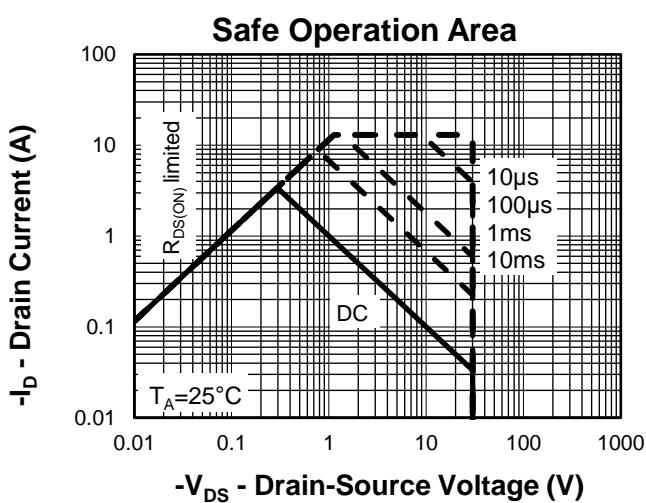
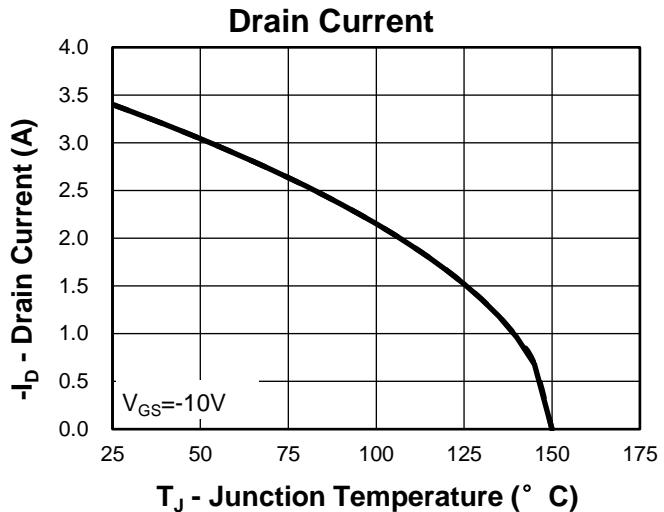
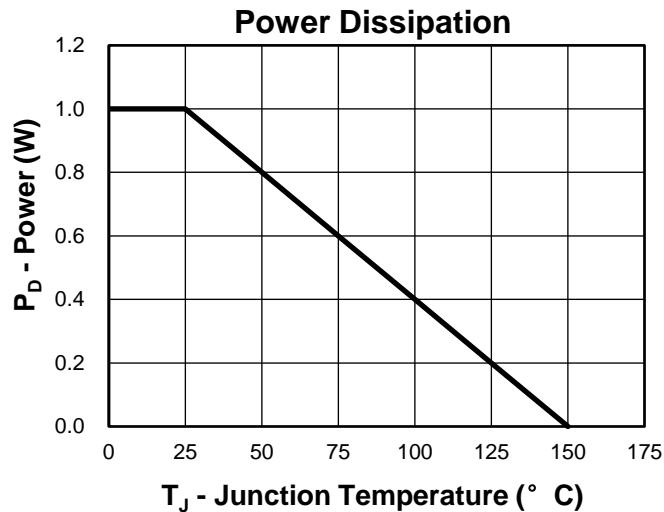
Device	Package	Packaging	Quantity	Reel Size	Tape width
KS3369AA	SOT23	Tape&Reel	3000	7"	8mm



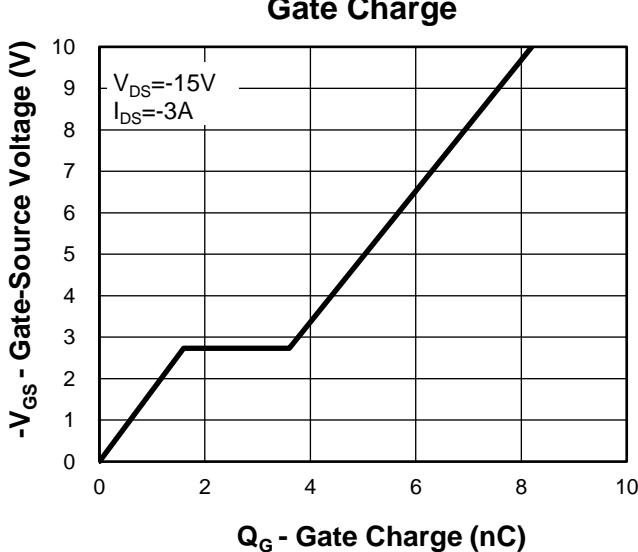
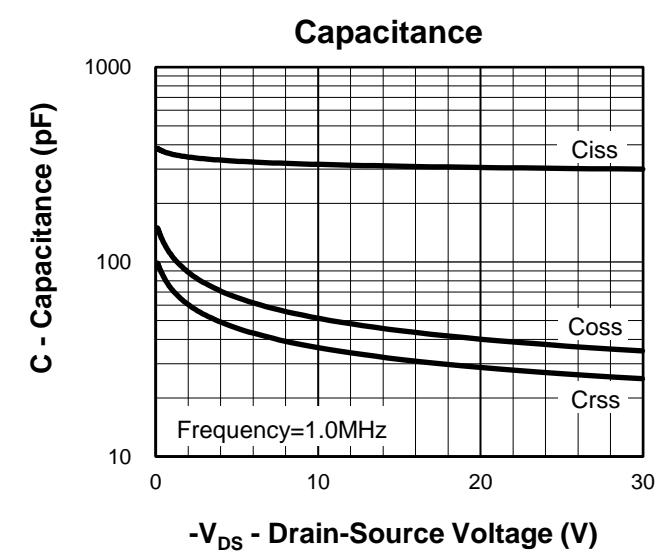
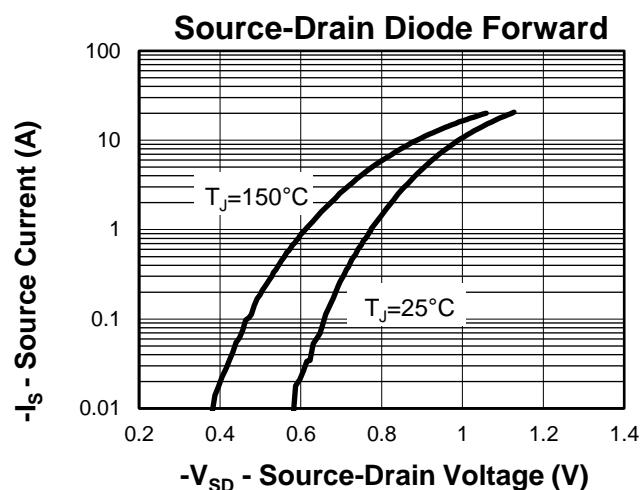
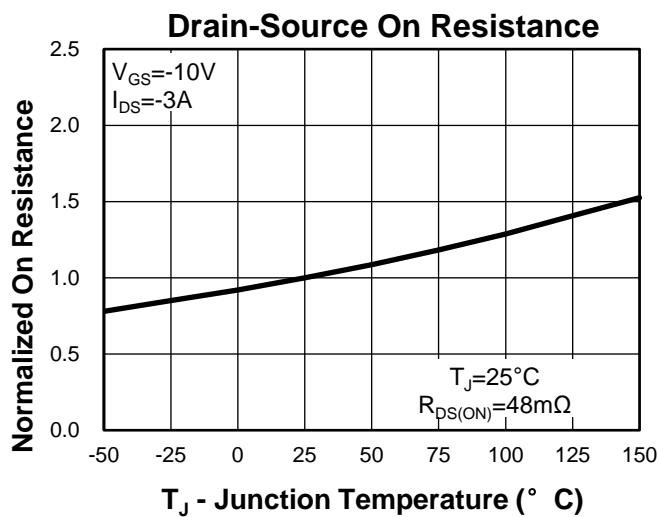
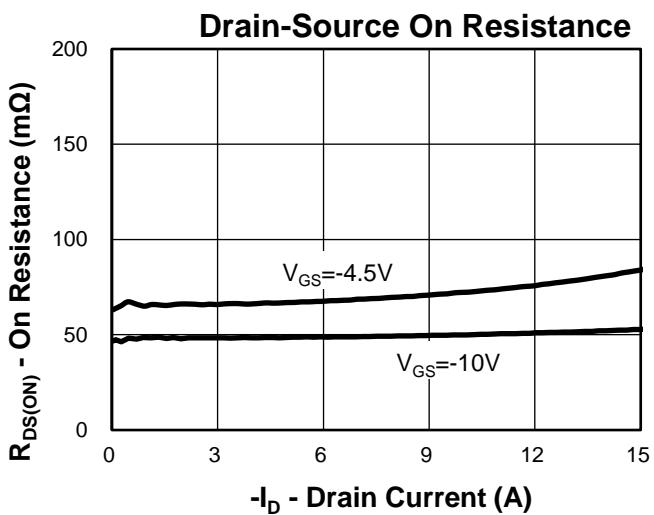
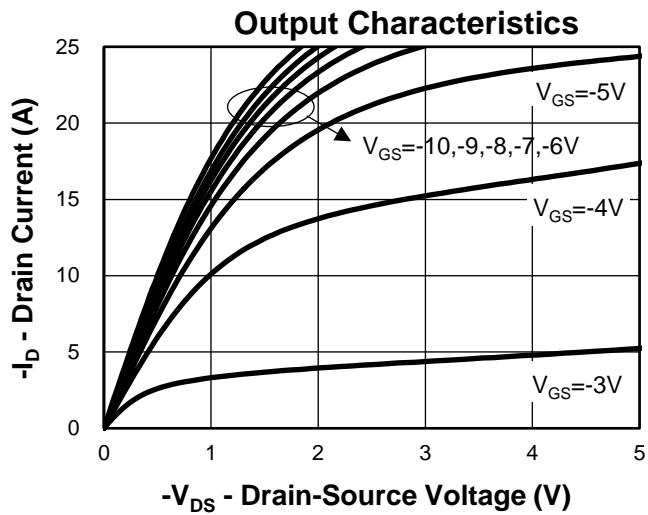
Y =Year,2017-A,2018-B,etc.

M =Month,Jan-1,Feb-2,...,Sep-9,Oct-A,Nov-B,Dec-C.

Typical Characteristics

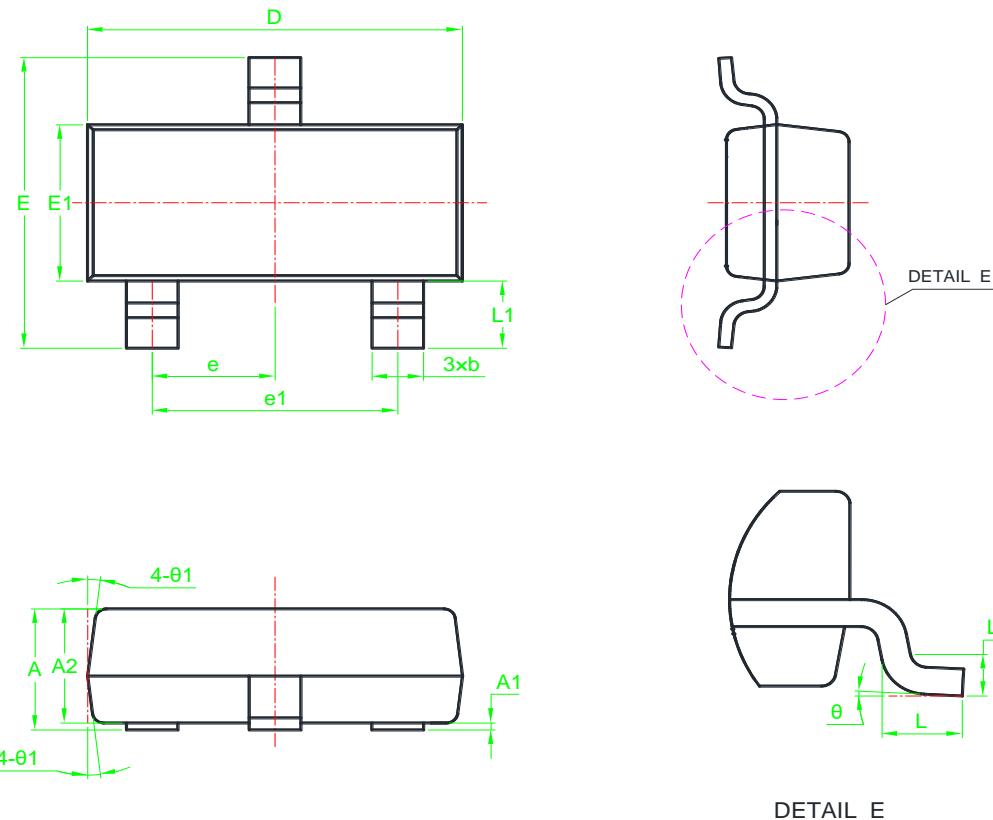


Typical Characteristics



Package Information

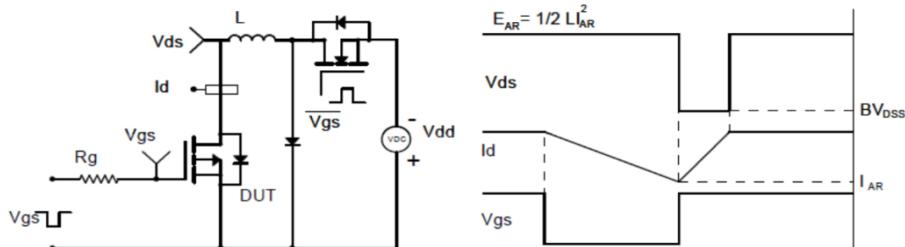
SOT23



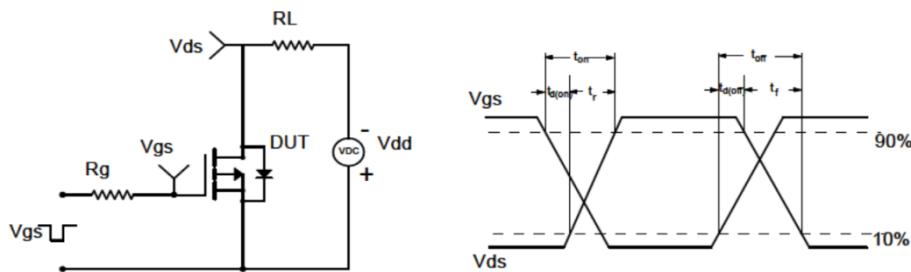
SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX		MIN	NOM	MAX	MIN	NOM	MAX
A	0.90	*	1.12	0.035	*	0.044	e	0.95BSC			0.037BSC		
A1	0.01	*	0.10	0.000	*	0.004	e1	1.90BSC			0.075BSC		
A2	0.80	0.90	1.02	0.031	0.035	0.040	L	0.30	0.40	0.50	0.012	0.016	0.020
b	0.30	0.40	0.50	0.012	0.016	0.020	L1	0.54REF			0.021REF		
D	2.80	2.90	3.00	0.110	0.114	0.118	L2	0.254BSC			0.010BSC		
E	2.25	2.40	2.55	0.089	0.094	0.100	θ	0°	*	8°	0°	*	8°
E1	1.20	1.30	1.40	0.047	0.051	0.055	θ1	0°	*	10°	0°	*	10°

Note: Dimensions do not include burrs and mold flash.

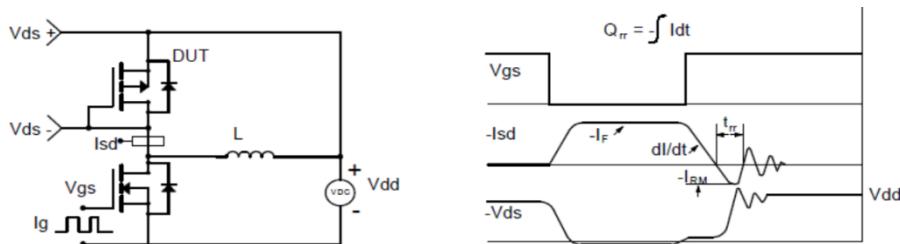
Avalanche Test Circuit and Waveforms



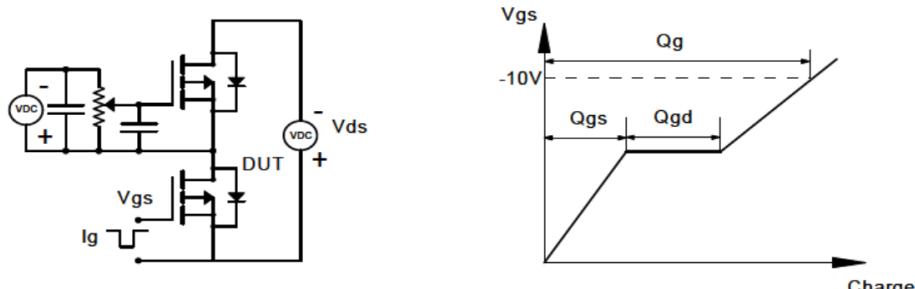
Switching Time Test Circuit and Waveforms



Diode Recovery Test Circuit and Waveforms



Gate Charge Test Circuit and Waveform



Customer Service

Kwansemi Semiconductor Co.,Ltd

Email:Sales@kwansemi.com

Web:www.kwansemi.com

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